

HAT1091C

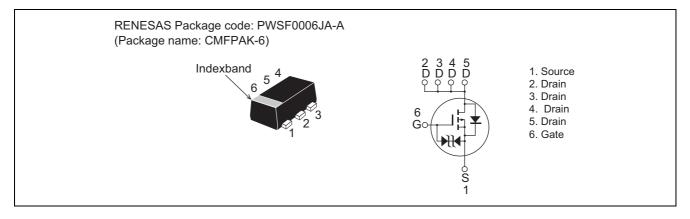
Silicon P Channel MOS FET Power Switching

> REJ03G1229-0400 Rev.4.00 Jun. 13, 2005

Features

- Low on-resistance $R_{DS(on)} = 134 \text{ m}\Omega \text{ typ.} (at V_{GS} = -4.5 \text{ V})$
- Low drive current.
- 2.5 V gate drive devices.
- High density mounting

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to Source voltage	V _{DSS}	-20	V
Gate to Source voltage	V _{GSS}	±12	V
Drain current	ID	-1.5	A
Drain peak current	I _D (pulse) ^{Note1}	-6	A
Body - Drain diode reverse drain current	I _{DR}	-1.5	A
Channel dissipation	Pch ^{Note 2}	830	mW
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	۵°

Notes 1. $PW \le 10 \ \mu s$, duty cycle $\le 1\%$

2. When using the glass epoxy board. (FR4 40 \times 40 \times 1.6mm), Ta = 25 $^{\circ}\text{C}$



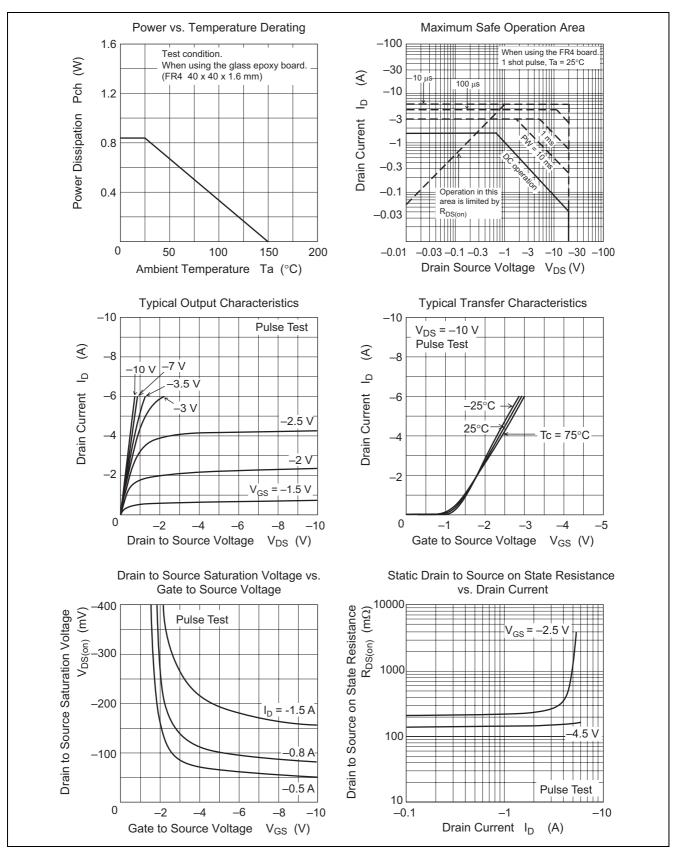
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
ltem	Symbol	Min.	Тур.	Max.	Unit	Test Conditions
Drain to Source breakdown voltage	V _{(BR)DSS}	-20	—	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to Source breakdown voltage	V _{(BR)GSS}	±12	—	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to Source leakage current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0$
Drain to Source leakage current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -20 V, V_{GS} = 0$
Gate to Source cutoff voltage	V _{GS(th)}	-0.4	—	-1.4	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}^{\text{Note3}}$
Drain to Source on state resistance	R _{DS(on)}	_	134	175	mΩ	$I_D = -0.8 \text{ A}, V_{GS} = -4.5 \text{ V}^{\text{Note3}}$
		_	205	287	mΩ	$I_D = -0.7 \text{ A}, V_{GS} = -2.5 \text{ V}^{\text{Note3}}$
Forward transfer admittance	y _{fs}	1.5	2.3		S	$I_D = -0.8 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note3}}$
Input capacitance	Ciss	_	200		pF	$V_{DS} = -10 V, V_{GS} = 0,$
Output capacitance	Coss	_	60		pF	f = 1 MHz
Reverse transfer capacitance	Crss	—	40		pF	
Total gate charge	Qg	_	2.6	_	nC	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V},$ $I_D = -1.5 \text{ A}$
Gate to Source charge	Qgs	_	0.7	_	nC	
Gate to Drain charge	Qgd	_	0.7	_	nC	
Turn - on delay time	t _{d(on)}	_	13	_	ns	$\label{eq:VDS} \begin{array}{l} V_{DS} = -10 \ V, \ V_{GS} = -4.5 \ V, \\ I_D = -0.8 \ A, \ R_L = 12.5 \ \Omega, \\ R_g = 4.7 \ \Omega \end{array}$
Rise time	tr	_	26	_	ns	
Turn - off delay time	t _{d(off)}	_	30	_	ns	
Fall time	t _f	_	9	_	ns	
Body - Drain diode forward voltage	V _{DF}	_	-0.85	-1.1	V	$I_F = -1.5 \text{ A}, V_{GS} = 0$

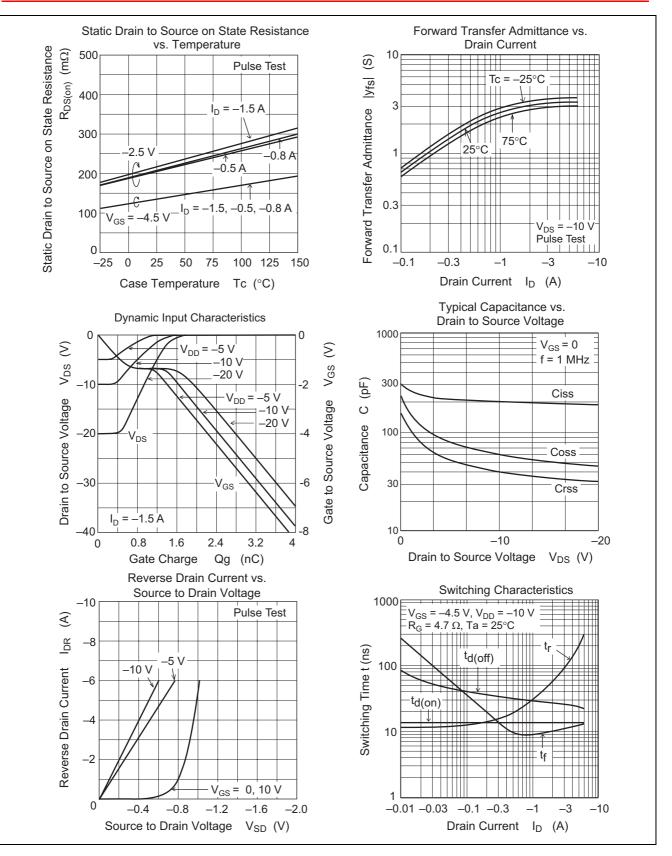
Notes: 3. Pulse test



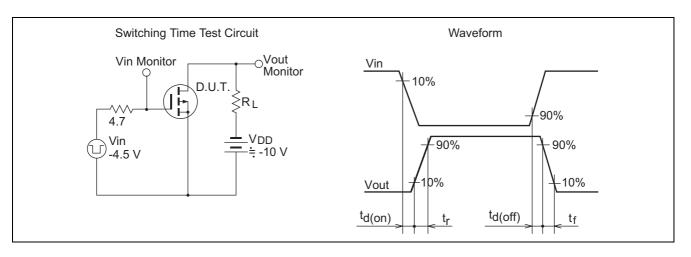
Main Characteristics





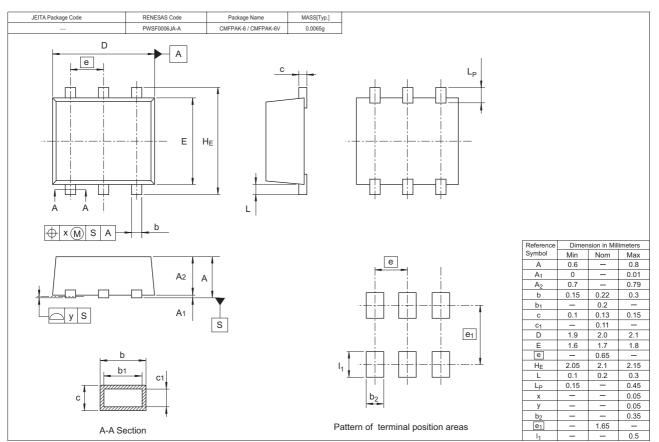


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Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT1091C-EL-E	3000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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